# Switching (-30V, -5.0A)

# RSS050P03

#### Features

- 1) Low On-resistance.
- 2) Built-in G-S Protection Diode.
- 3) Small and Surface Mount Package (SOP8).

#### Application

Power switching, DC / DC converter.

#### ●Structure

Silicon P-channel MOS FET

# Packaging specifications

	Package	Taping
Type	Code	TB
	Basic ordering unit (pieces)	2500
RSS050P03		0

# ● Absolute maximum ratings (Ta=25°C)

Parameter		Symbol	Limits	Unit	
Drain-source voltage		V <sub>DSS</sub>	-30	V	
Gate-source voltage		Vgss	±20	V	
Drain current	Continuous	ID	±5.0	Α	
	Pulsed	IDP	±20	A *1	
Source current (Body diode)	Continuous	Is	-1.6	Α	
	Pulsed	Isp	-20	A *1	
Total power dissipation		P <sub>D</sub>	2.0	W *2	
Channel temperature		Tch	150	°C	
Range of Storage temperature		Tstg	-55 to +150	°C	

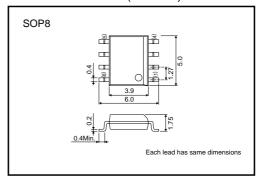
<sup>\*1</sup> Pw≤10µs, Duty cycle≤1% \*2 Mounted on a ceramic board

# ●Thermal resistance (Ta=25°C)

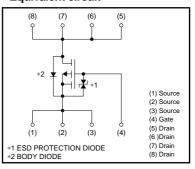
Parameter	Symbol	Limits	Unit	
Channel to ambient	Rth (ch-a)	62.5	°C / W	*

<sup>\*</sup> Mounted on a ceramic board.

# ●External dimensions (Unit : mm)



# ●Equivalent circuit



# ●Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Gate-source leakage	I <sub>GSS</sub>	-	_	±10	μΑ	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V
Drain-source breakdown voltage	V <sub>(BR) DSS</sub>	-30	_	_	٧	I <sub>D</sub> = -1mA, V <sub>GS</sub> =0V
Zero gate voltage drain current	IDSS	_	_	-1	μΑ	V <sub>DS</sub> = -30V, V <sub>GS</sub> =0V
Gate threshold voltage	V <sub>GS (th)</sub>	-1.0	_	-2.5	٧	V <sub>DS</sub> = -10V, I <sub>D</sub> = -1mA
Static drain-source on-state resistance	R <sub>DS (on)</sub> *	-	30	42	mΩ	I <sub>D</sub> = -5.0A, V <sub>G</sub> s= -10V
		-	47	65	mΩ	I <sub>D</sub> = -2.5A, V <sub>G</sub> S= -4.5V
		_	55	77	mΩ	I <sub>D</sub> = -2.5A, V <sub>G</sub> s= -4.0V
Forward transfer admittance	Y <sub>fs</sub> *	5.0	_	_	S	V <sub>DS</sub> = -10V, I <sub>D</sub> = -2.5A
Input capacitance	Ciss	_	1200	_	pF	V <sub>DS</sub> = -10V
Output capacitance	Coss	-	250	_	pF	V <sub>GS</sub> =0V
Reverse transfer capacitance	Crss	-	180	_	pF	f=1MHz
Turn-on delay time	td (on) *	-	12	_	ns	I <sub>D</sub> = -2.5A
Rise time	tr *	_	25	_	ns	V <sub>DD</sub> ≒ −15V
Turn-off delay time	t <sub>d (off)</sub> *	_	70	_	ns	V <sub>GS</sub> = -10V R <sub>L</sub> =6Ω
Fall time	t <sub>f</sub> *	_	35	_	ns	Rgs=10Ω
Total gate charge	Qg	_	13	_	nC	V <sub>DD</sub> ≒-15V
Gate-source charge	Qgs	_	2.8	_	nC	V <sub>GS</sub> = -5V
Gate-drain charge	Q <sub>gd</sub>	_	5.0	_	nC	I <sub>D</sub> = -5.0A

\*Pulsed

Body diode characteristics (source-drain characteristics)

 Forward voltage
 Vsb
 -1.2
 V
 Is= -1.6A, Vgs=0V

#### Electrical characteristic curves

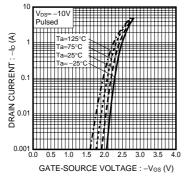


Fig.1 Typical Transfer Characteristics

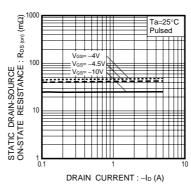


Fig.2 Static Drain-Source On-State Resistance vs. Drain Current

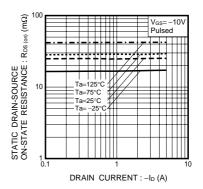


Fig.3 Static Drain-Source On-State Resistance vs. Drain Current

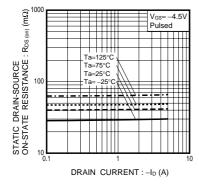


Fig.4 Static Drain-Source On-State vs. Drain Current

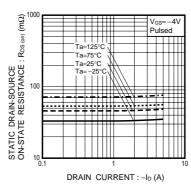


Fig.5 Static Drain-Source On-State vs. Drain Current

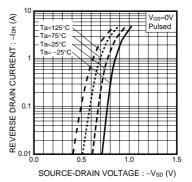


Fig.6 Reverse Drain Current Source-Drain Current

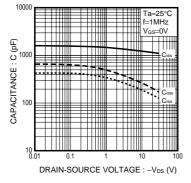


Fig.7 Typical Capacitance vs. Drain-Source Voltage

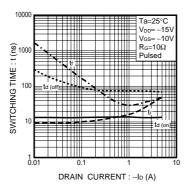


Fig.8 Switching Characteristics

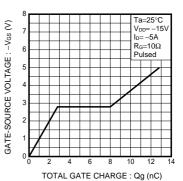


Fig.9 Dynamic Input Characteristics

### ●Measurement circuits

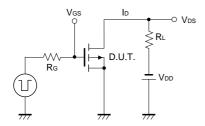


Fig.10 Switching Time Test Circuit

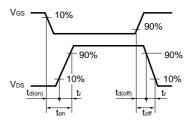


Fig.11 Switching Time Waveforms

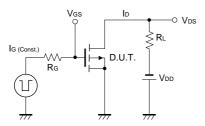


Fig.12 Gate Charge Test Circuit

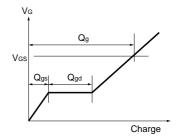


Fig.13 Gate Charge Waveform

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